



SOT1338-1

plastic extremely thin small outline package; no leads; 6 terminals; body 2.0 x 2.0 x 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON6
Package type industry code	HXSON6
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-9-2012

Table 1. Package summary

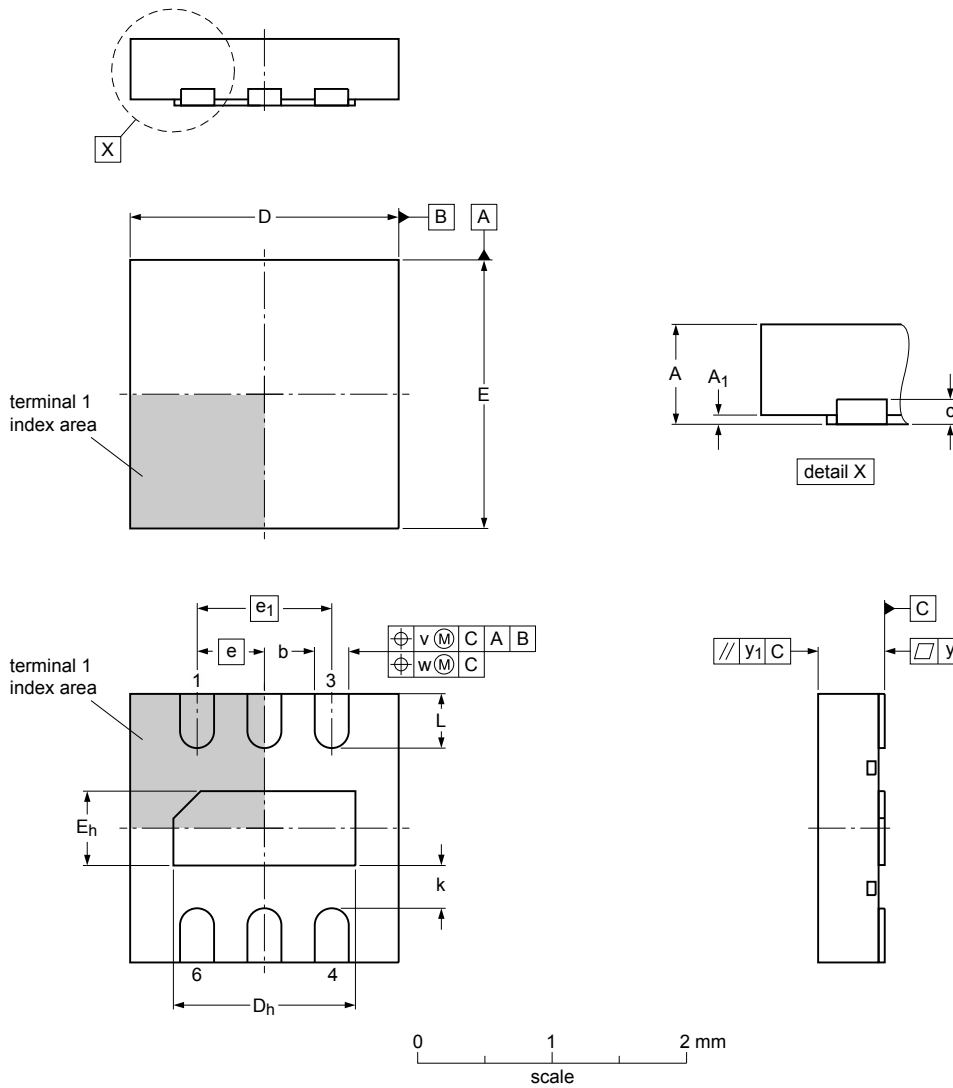
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

HXSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 2.0 x 2.0 x 0.5 mm SOT1338-1



Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	b	c	D	D _h	E	E _h	e	e ₁	k	L	v	w	y	y ₁
max	0.5	0.05	0.30	0.152	2.1	1.40	2.1	0.60				0.5				
mm nom			0.25		2.0	1.35	2.0	0.55	0.5	1.0		0.4	0.1	0.05	0.05	0.05
min		0.00	0.20	0.050	1.9	1.30	1.9	0.50			0.2	0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1338-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1338-1	---	---	---		12-08-06 12-08-30

Fig. 1. Package outline HXSON6 (SOT1338-1)

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3. Legal information

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